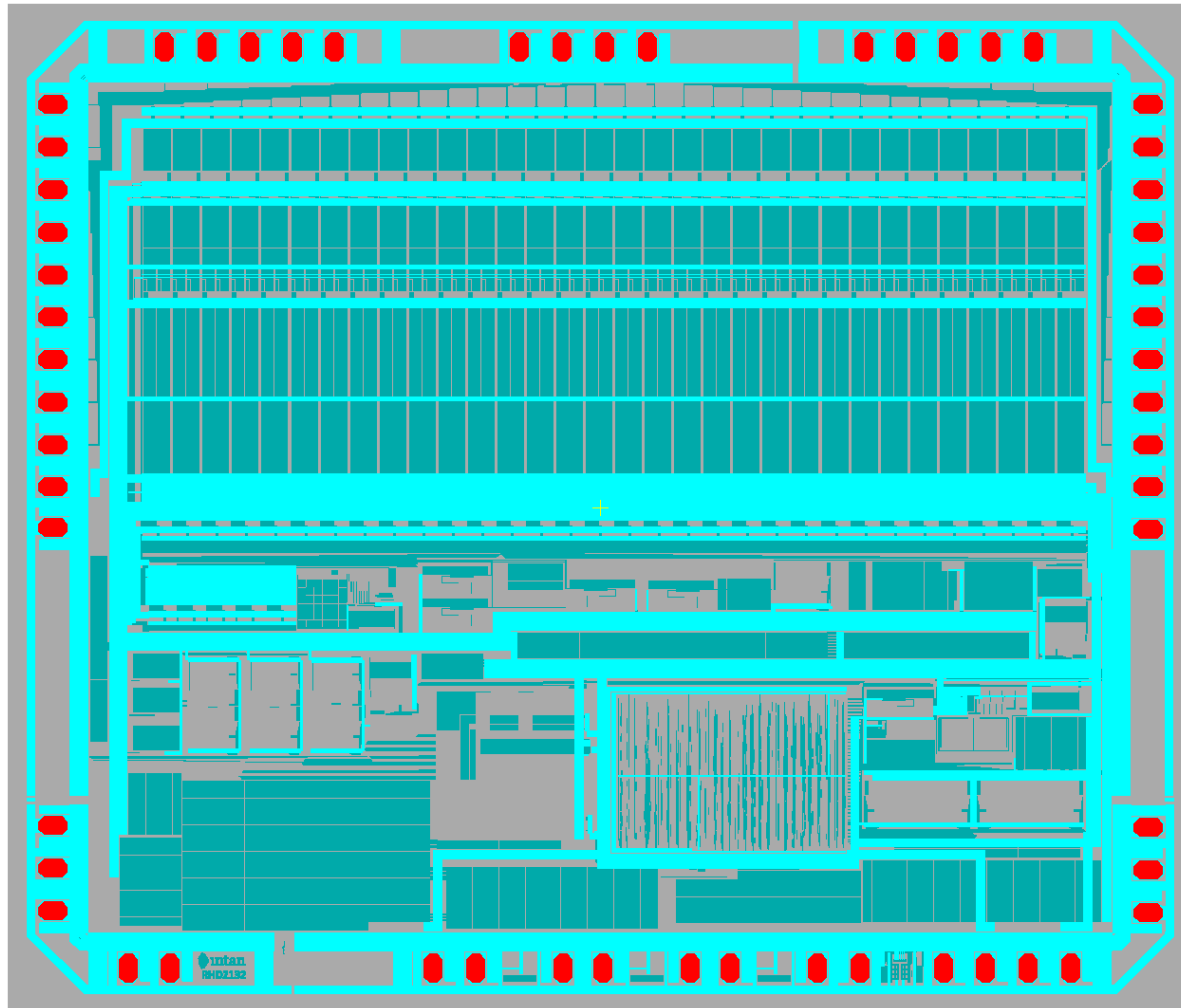
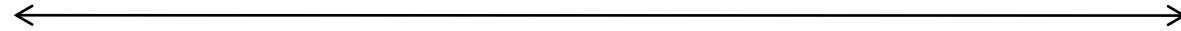


# Intan Technologies RHD2132 Bare Die

Approximately 4.8 mm



**Gray** = approximate outline of die (may vary from die to die due to variations in sawing)

**Yellow Cross** = center of design (may not coincide precisely with center of die due to variations in sawing)

**Blue, Green** = top metal layers (highly visible)

**Red** = glass openings for bond pads



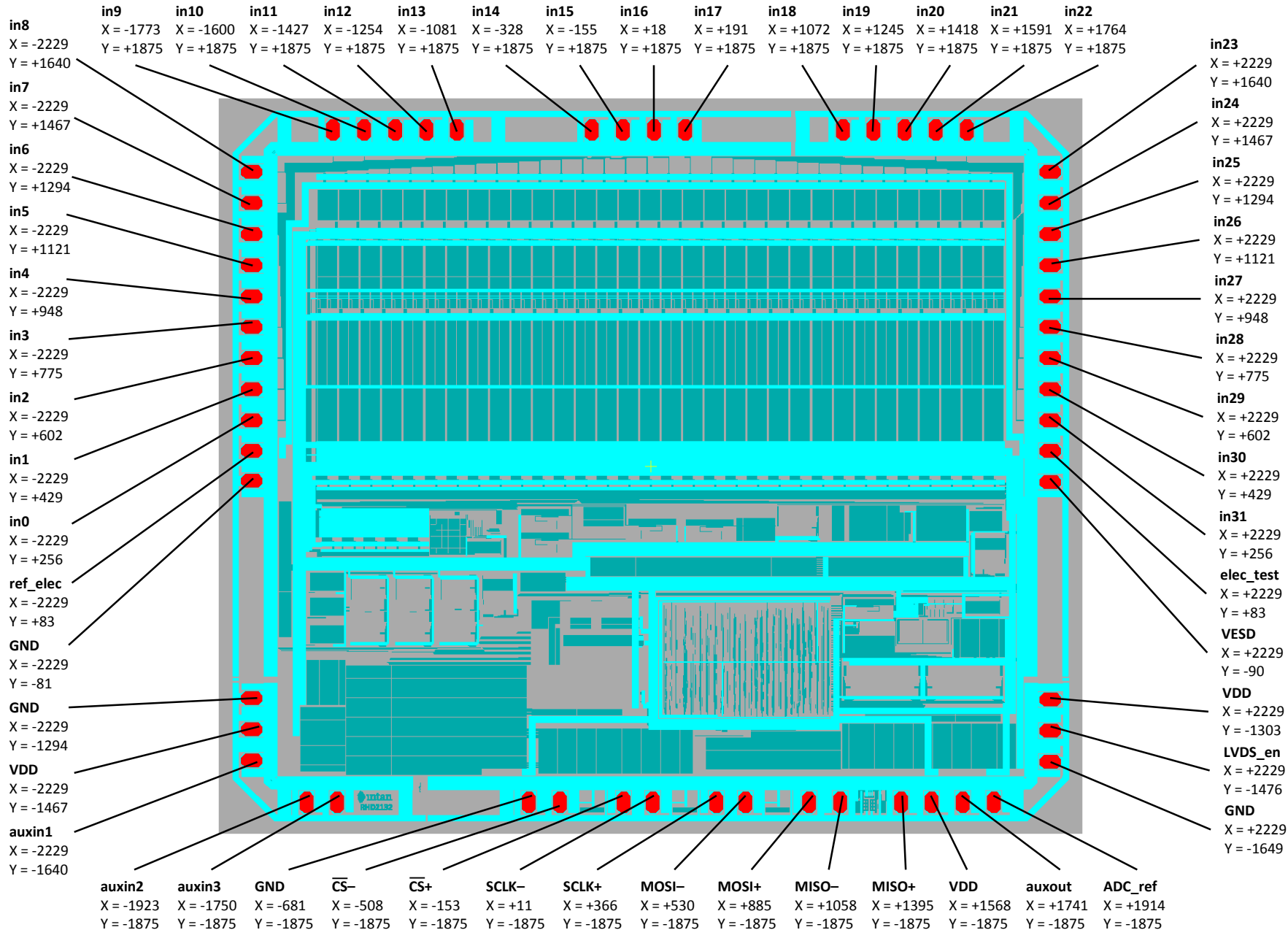
Approximately 4.1 mm

Each die is 0.20 mm (8 mils) thick

# RHD2132

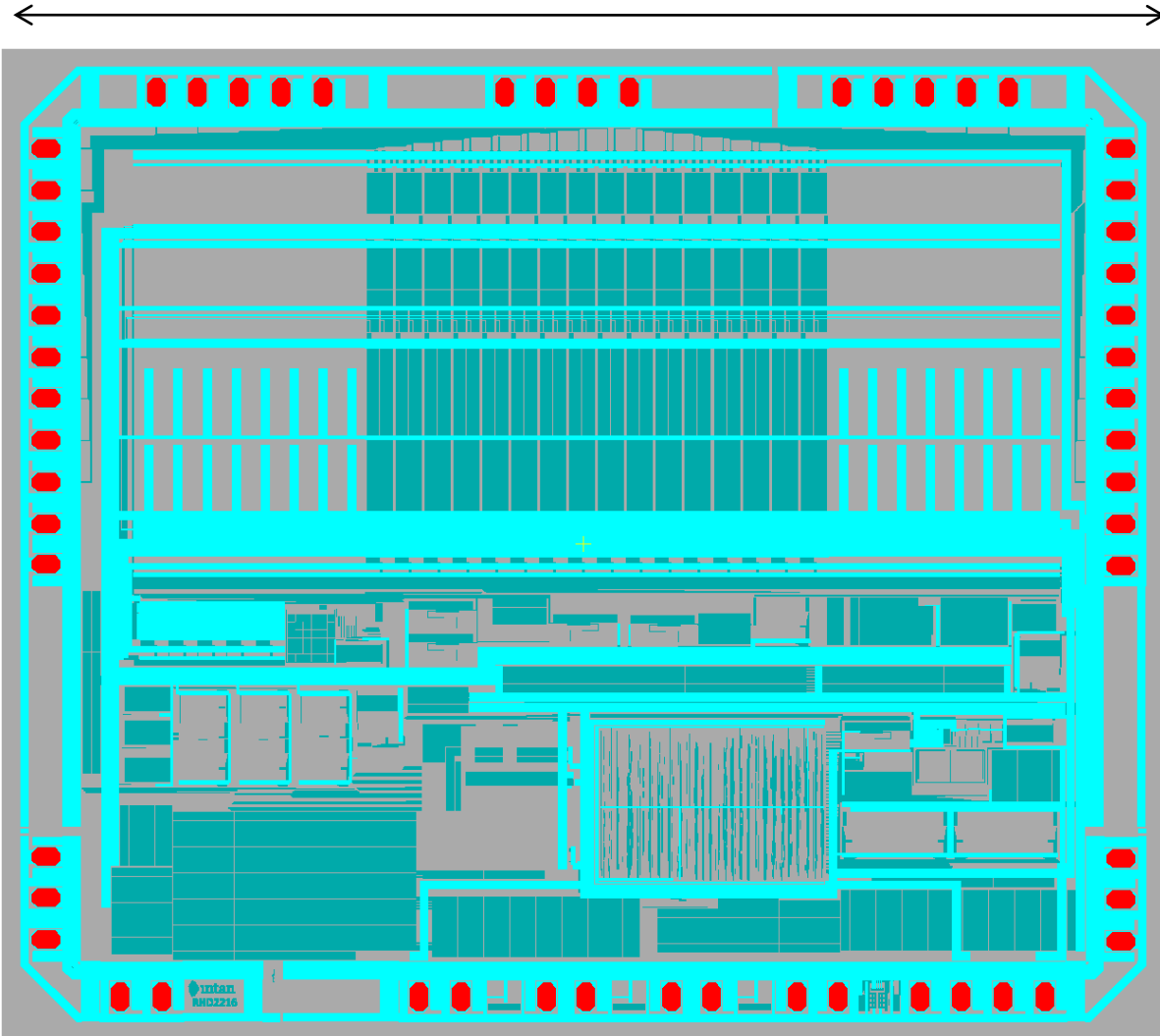
# Coordinates of Bond Pad Centers, Relative to Center of Design

dimensions in microns



# Intan Technologies RHD2216 Bare Die

Approximately 4.8 mm



**Gray** = approximate outline of die (may vary from die to die due to variations in sawing)

**Yellow Cross** = center of design (may not coincide precisely with center of die due to variations in sawing)

**Blue, Green** = top metal layers (highly visible)

**Red** = glass openings for bond pads

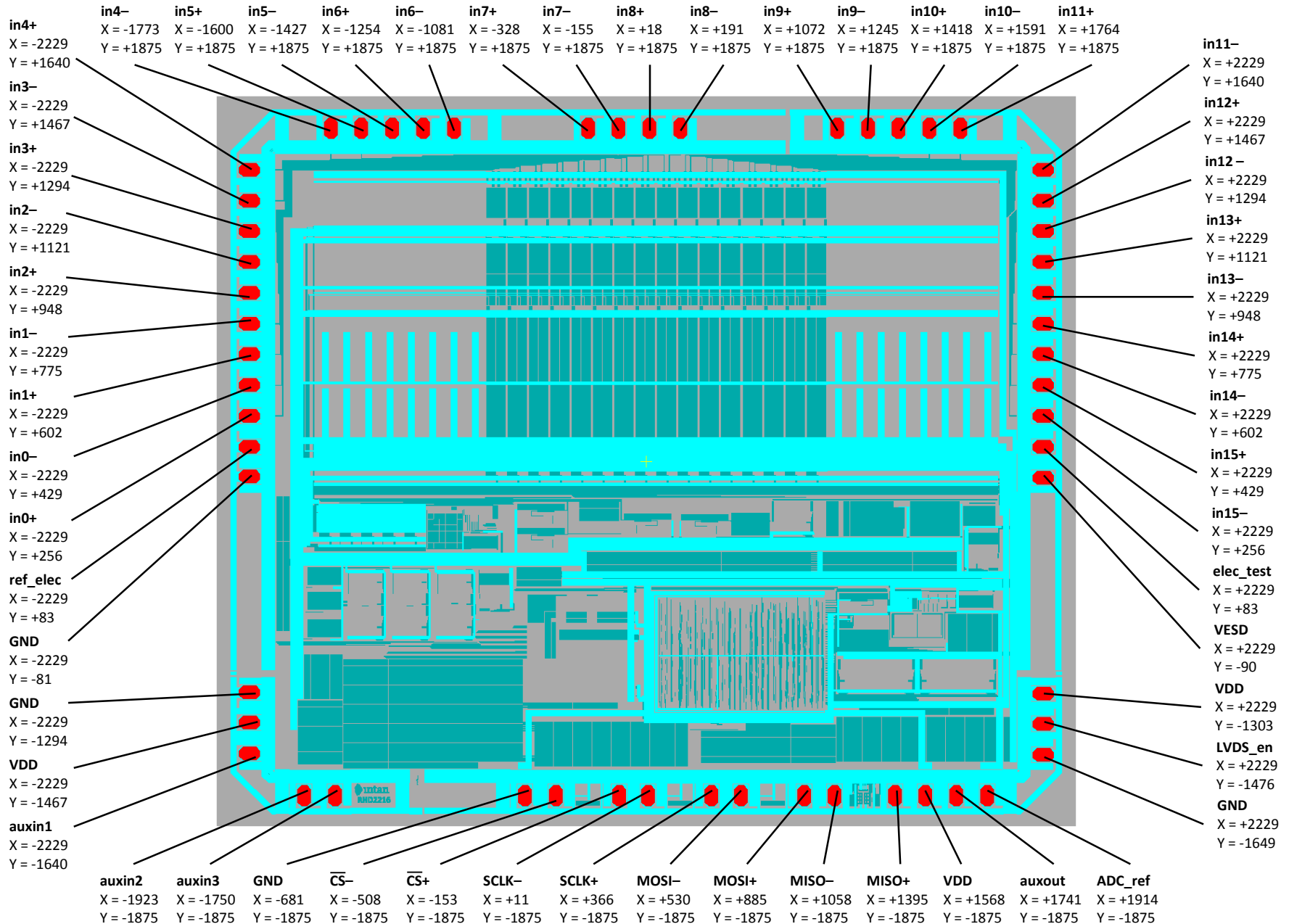
Approximately 4.1 mm

Each die is 0.20 mm (8 mils) thick

# RHD2216

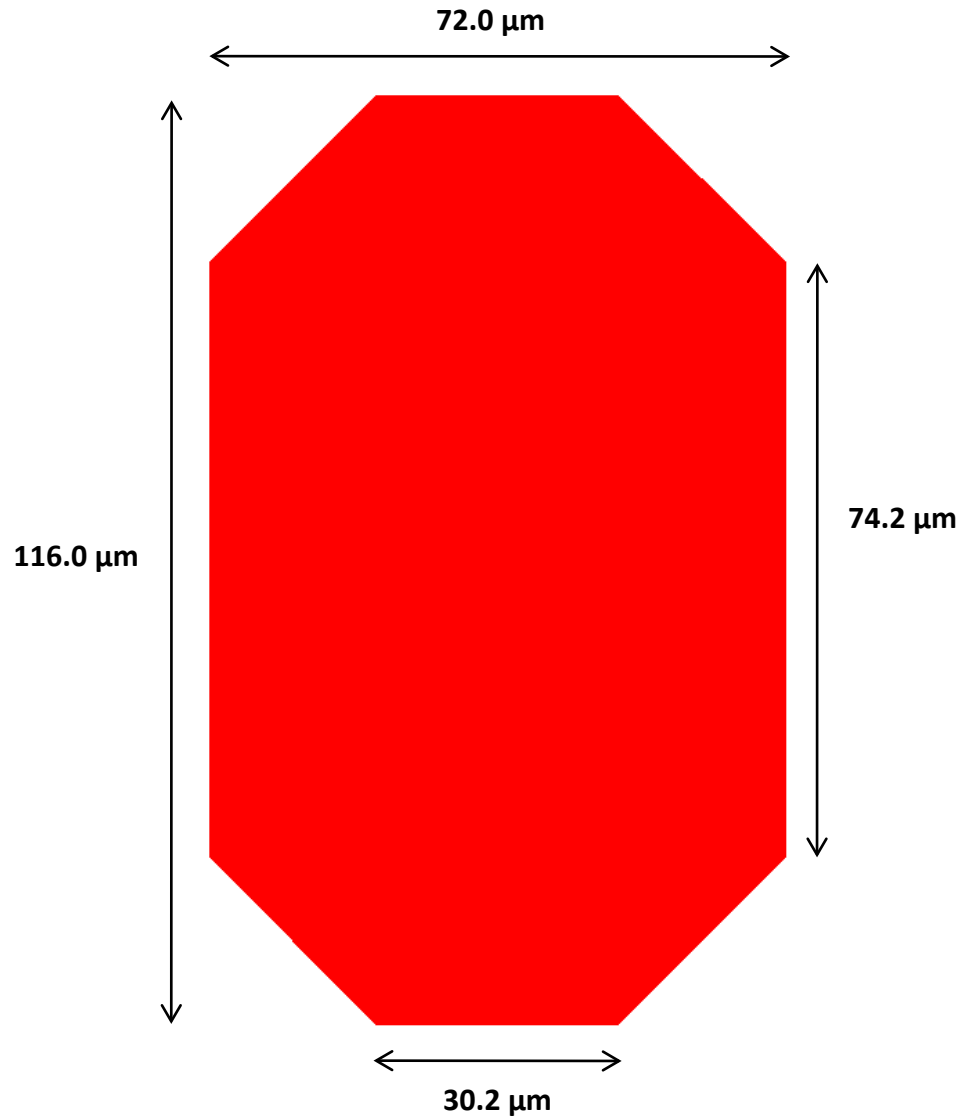
# Coordinates of Bond Pad Centers, Relative to Center of Design

dimensions in microns



# Bond Pad Dimensions

Bond pad metal: AlCu (99.5% aluminum, 0.5% copper)



Minimum bond pad pitch (center to center) on 16- and 32-channel chips:  $164\ \mu\text{m}$